

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

5 1 (previously presented): A chip-packaging with bonding options having a plurality of package substrates, comprising:

a first package substrate having a high voltage or a low voltage;

a second package substrate having a high voltage or a low voltage, the voltage level of the first package substrate being the logical opposite of the voltage level of the second package substrate; and

a chip mounted on first package substrate, the chip comprising a plurality of bonding option pads,

wherein each bonding option pad of the chip is associated with at least two bonding options respectively provided by the first package substrate and the second package substrate, and each bonding option pad is connected to one of the first package substrate and the second package substrate.

10 2 (cancelled).

15 20 3 (previously presented): The chip-packaging of the claim 1 wherein the high voltage is the voltage of the power supply and the low voltage is the ground voltage.

25 4 (currently amended): The chip-packaging of the claim 1 further comprising a plurality of leads, wherein each lead is connected to a high voltage, a low voltage, or an input/output signal one pin of the chip packaging.

5-6 (cancelled).

7 (original): The chip-packaging of the claim 1 wherein the first package substrate extends outside the chip and the second package substrate surrounds the chip.

5 8 (previously presented): The chip-packaging of the claim 1 wherein the first package substrate and the second package substrate substantially approximate each of a plurality of the bonding option pads.

9-19 (cancelled).

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20 (previously presented): The chip-packaging of the claim 1 further comprising a plurality of leads, each bonding option pad of the chip having a corresponding lead, wherein each bonding option pad is connected to one of the first package substrate, the second package substrate, and the corresponding lead.

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21 (new): The chip-packaging of the claim 1 wherein each bonding option pad is connected to one of the first package substrate and the second package substrate for determining the functionality of the chip.

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